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FDN357N

N-Channel Logic Level Enhancement Mode Field Effect Transistor

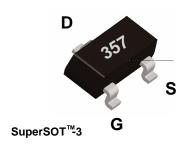
General Description

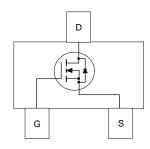
SuperSOT[™]-3 N-Channel logic level enhancement mode power field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage applications in notebook computers, portable phones, PCMCIA cards, and other battery powered circuits where fast switching, and low in-line power loss are needed in a very small outline surface mount package.

Features

- 1.9 A, 30 V, $R_{DS(ON)} = 0.090 \Omega$ @ $V_{GS} = 4.5 V$ $R_{DS(ON)} = 0.060 \Omega$ @ $V_{GS} = 10 V$.
- Industry standard outline SOT-23 surface mount package using proprietary SuperSOTTM-3 design for superior thermal and electrical capabilities.
- High density cell design for extremely low R_{DS(ON)}.
- Exceptional on-resistance and maximum DC current capability.







Absolute Maximum Ratings $T_A = 25^{\circ}\text{C}$ unless other wise noted

| Symbol | Parameter | | FDN357N | Units |
|--------------------|---|---------|------------|----------|
| V _{DSS} | Drain-Source Voltage | | 30 | V |
| / _{GSS} | Gate-Source Voltage - Continuous | | ±20 | V |
| l _D | Drain/Output Current - Continuous | | 1.9 | А |
| | - Pulsed | | 10 | |
| P_{D} | Maximum Power Dissipation (No | ote 1a) | 0.5 | W |
| | (No | ite 1b) | 0.46 | |
| J,T _{STG} | Operating and Storage Temperature Range | | -55 to 150 | °C |
| HERMA | L CHARACTERISTICS | | | <u>.</u> |
| R _{OJA} | Thermal Resistance, Junction-to-Ambient (Note 1a) | | 250 | °C/W |
| R _{euc} | Thermal Resistance, Junction-to-Case (Note 1) | | 75 | °C/W |

| Symbol | Parameter | Conditions | | Min | Тур | Max | Units |
|--|---|---|-----------------------|-----|-------|------|-----------|
| OFF CHAR | ACTERISTICS | • | | • | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$ | | 30 | | | V |
| Δ BV _{DSS} / Δ T _J | Breakdown Voltage Temp. Coefficient | I _D = 250 μA, Referenced to 25 °C | | | 36 | | mV/°C |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} = 24 V, V _{GS} = 0 V | | | | 1 | μA |
| | | | T _. = 55°C | | | 10 | μA |
| I _{GSSF} | Gate - Body Leakage, Forward | $V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$ | | | | 100 | nA |
| I _{GSSR} | Gate - Body Leakage, Reverse | $V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$ | | | | -100 | nA |
| | CTERISTICS (Note) | 1 00 30 | | | | I | <u>-1</u> |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$ | | 1 | 1.6 | 2 | V |
| $\Delta V_{GS(th)}/\Delta T_J$ | Gate Threshold Voltage Temp. Coefficient | I _D = 250 μA, Referenced to 25 °C | | | -3.6 | | mV/°C |
| R _{DS(ON)} | Static Drain-Source On-Resistance | $V_{GS} = 4.5 \text{ V}, I_{D} = 1.9 \text{ A}$ | | | 0.081 | 0.09 | Ω |
| 20(0.1) | | | T ₁ =125°C | | 0.11 | 0.14 | 1 |
| | | $V_{GS} = 10 \text{ V}, I_D = 2.2 \text{ A}$ | | | 0.053 | 0.06 | |
| I _{D(ON)} | On-State Drain Current | $V_{GS} = 4.5 \text{ V}, \ V_{DS} = 5 \text{ V}$ | | 5 | | | Α |
| g _{FS} | Forward Transconductance | $V_{DS} = 5 \text{ V}, I_{D} = 1.9 \text{ A}$ | | | 5 | | S |
| DYNAMIC C | HARACTERISTICS | • | | • | • | • | |
| C _{iss} | Input Capacitance | $V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1.0 \text{ MHz}$ | | | 235 | | pF |
| C _{oss} | Output Capacitance | | | | 145 | | pF |
| C _{rss} | Reverse Transfer Capacitance | | | | 50 | | pF |
| SWITCHING | CHARACTERISTICS (Note) | | | | | | |
| t _{D(on)} | Turn - On Delay Time | $V_{DD} = 10 \text{ V}, I_{D} = 1 \text{ A},$ $V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$ | | | 5 | 10 | ns |
| t, | Turn - On Rise Time | | | | 12 | 22 | ns |
| $t_{D(off)}$ | Turn - Off Delay Time | | | | 12 | 22 | ns |
| t, | Turn - Off Fall Time | | | | 3 | 8 | ns |
| Q_g | Total Gate Charge | $V_{DS} = 10 \text{ V}, I_{D} = 1.9 \text{ A},$ | | | 4.2 | 5.9 | nC |
| Q_{gs} | Gate-Source Charge | V _{GS} = 5 V | | | 1.3 | | nC |
| Q_{gd} | Gate-Drain Charge | | | | 1.7 | | nC |
| DRAIN-SOL | JRCE DIODE CHARACTERISTICS AND I | MAXIMUM RATINGS | | | | | |
| I _s | Maximum Continuous Drain-Source Diode Forward Current | | | | | 0.42 | Α |
| V_{SD} | Drain-Source Diode Forward Voltage | $V_{GS} = 0 \text{ V}, I_{S} = 0.42 \text{ A} \text{ (Note)}$ | | | 0.71 | 1.2 | V |

Note

Typical $R_{\theta,J_{t}}$ using the board layouts shown below on 4.5"x5" FR-4 PCB in a still air environment :



a. 250°C/W when mounted on a 0.02 in² pad of 2oz Cu.



b. 270°C/W when mounted on a 0.001 in² pad of 2oz Cu.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2.0%.

^{1.} $R_{g,N}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{g,C}$ is guaranteed by design while $R_{g,C}$ is determined by the user's board design.

Typical Electrical Characteristics

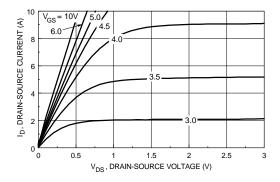


Figure 1. On-Region Characteristics.

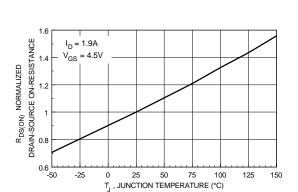


Figure 3. On-Resistance Variation with Temperature.

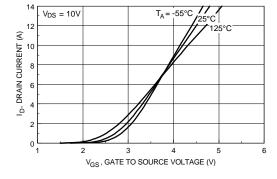


Figure 5. Transfer Characteristics.

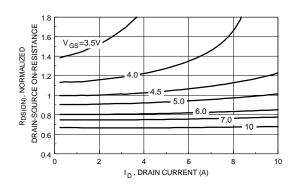


Figure 2. On-Resistance Variation with Drain Current and Gate

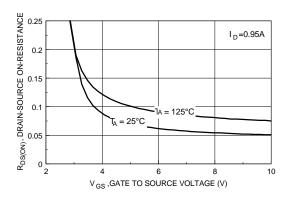


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

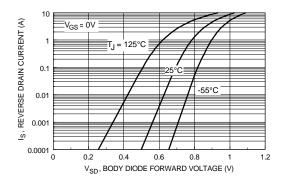


Figure 6. Body Diode Forward Voltage
Variation with Source Current
and Temperature.

Typical Electrical And Thermal Characteristics

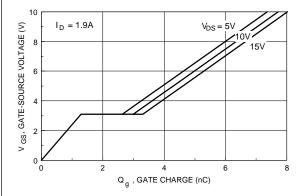


Figure 7. Gate Charge Characteristics.

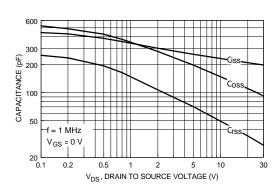


Figure 8. Capacitance Characteristics.

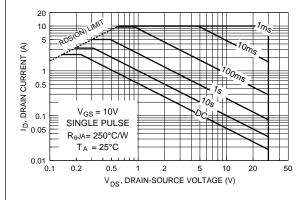


Figure 9. Maximum Safe Operating Area.

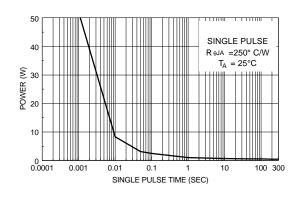


Figure 10. Single Pulse Maximum Power Dissipation.

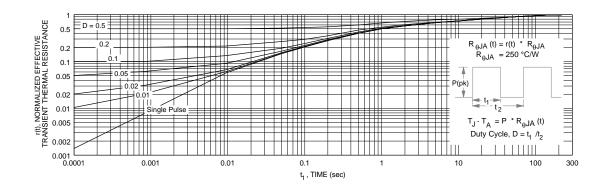


Figure 11. Transient Thermal Response Curve.

Note: Thermal characterization performed using the conditions described in note 1a. Transient thermal response will change depending on the circuit board design.

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